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A P P U N T I

STUDENTE: Caldera Filippo

MATERIA: Testing and fault tollerance - Prof. Sonza

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TFT

Testing and
Fault Tolerance

- M. Souto -

FILIPPO
CALDERA

TEST = detect the presence of a fault.

L1 10/06/17

Establish the probability of faults \Rightarrow Dependability

=
characteristic of a system when a
fault may produce a critical
behavior

1 Estimate $P(\text{failure})$

2 Act. to make the system work \hookrightarrow reduce $P(\text{failure})$ lower

Product specification = list of what the product is supposed to do.
↓
ALWAYS WRITTEN

MISSION = description of the function in the environment and their duration.

From the first idea to the ready-to-use product there is a long process = Life Cycle

↓
divided in phases

phases duration depend by the product

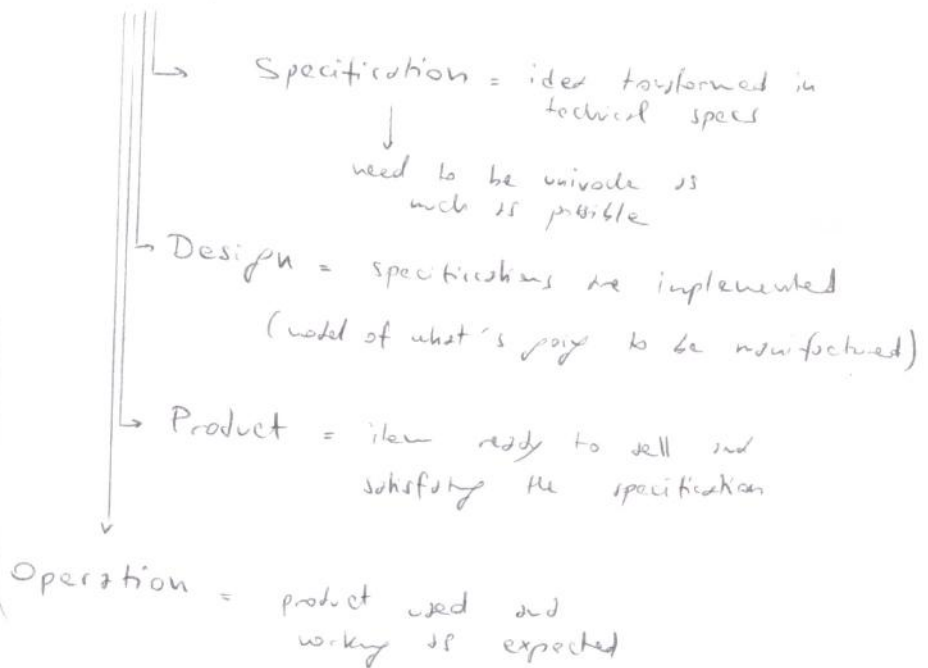
EX.

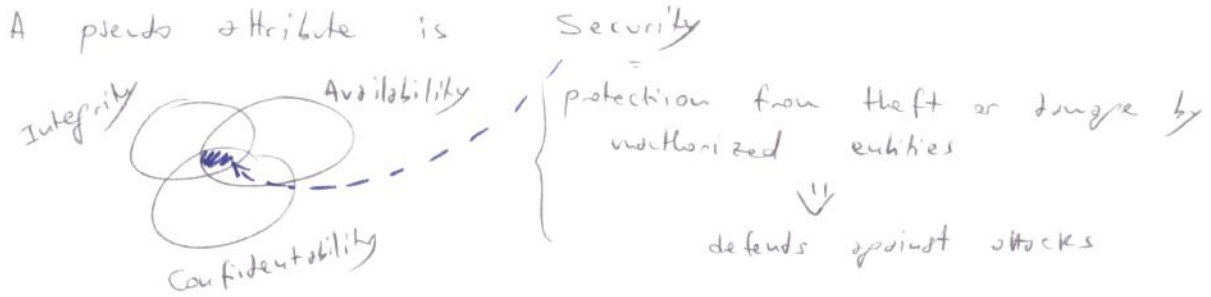
car ECU

Design last years → Operation last decade

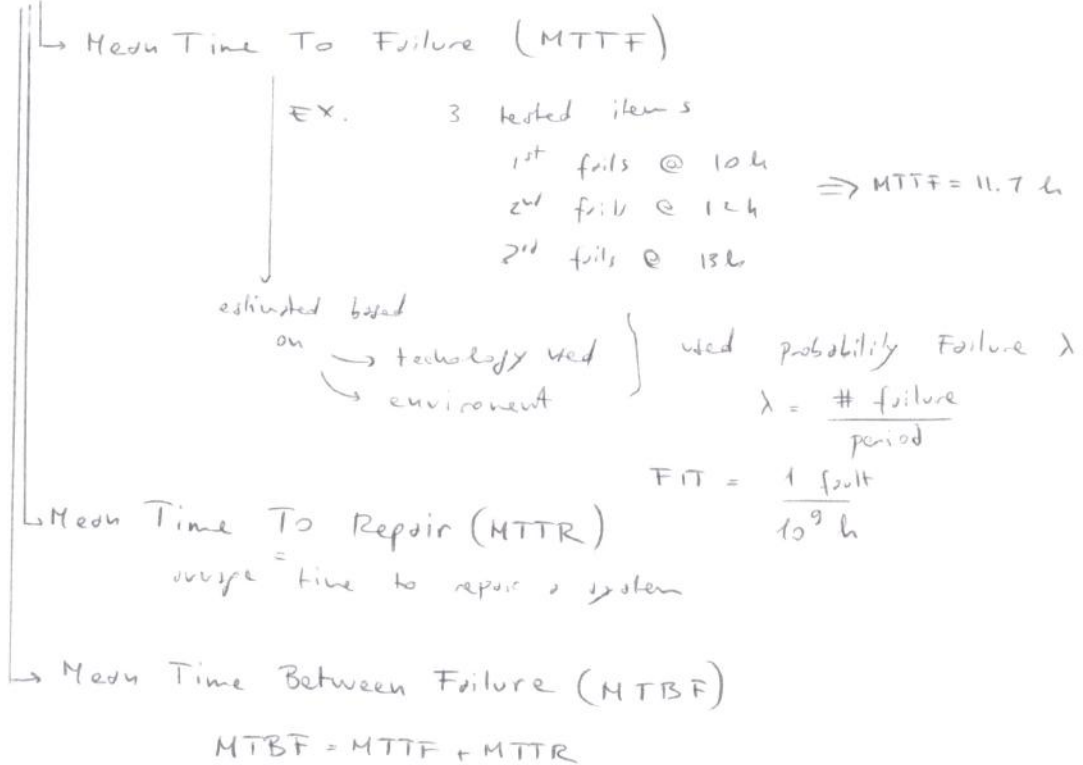
Space Launcher

Design lasts years → operation takes 30 min



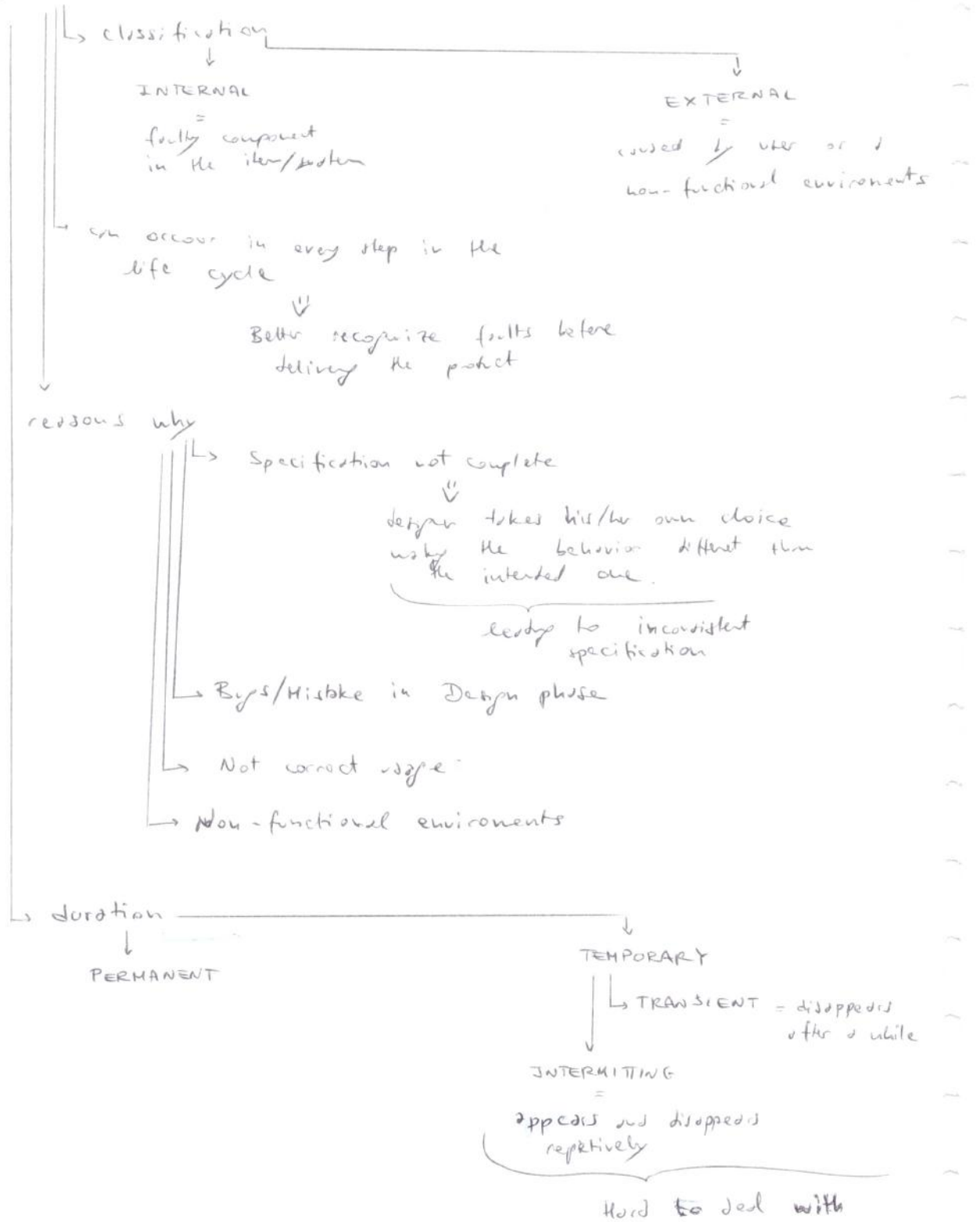


MEANS



THREATS = fault causes

FAULTS



L3 10/13/17

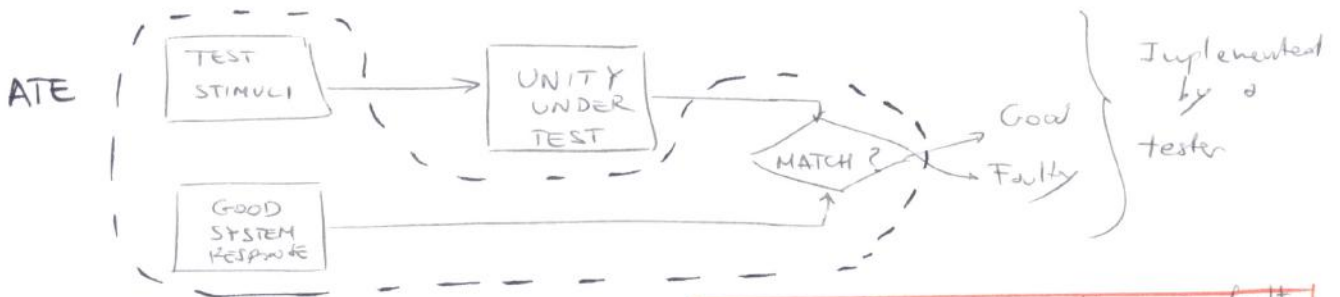
TEST = process to identify faults in projects

very important, especially in the design phase

uses Faults Models = Logical Faults = fault models

↓
makes testing easier ← Faults are generalized in classes of models

Testing Base scheme is



stimuli must be close in order to provoke fault, it prevents

In order to recognize a fault it need to produce a failure

V.I.

2 phases

TEST STIMULI GENERATION

choose the right stimuli in order to discover as much as possible of possible faults

done before manufacturing

cost depends by → UUT

↳ constraints

TEST APPLICATION

provide as input the stimuli chosen and check for failures

↓
compare system output with the expected ones

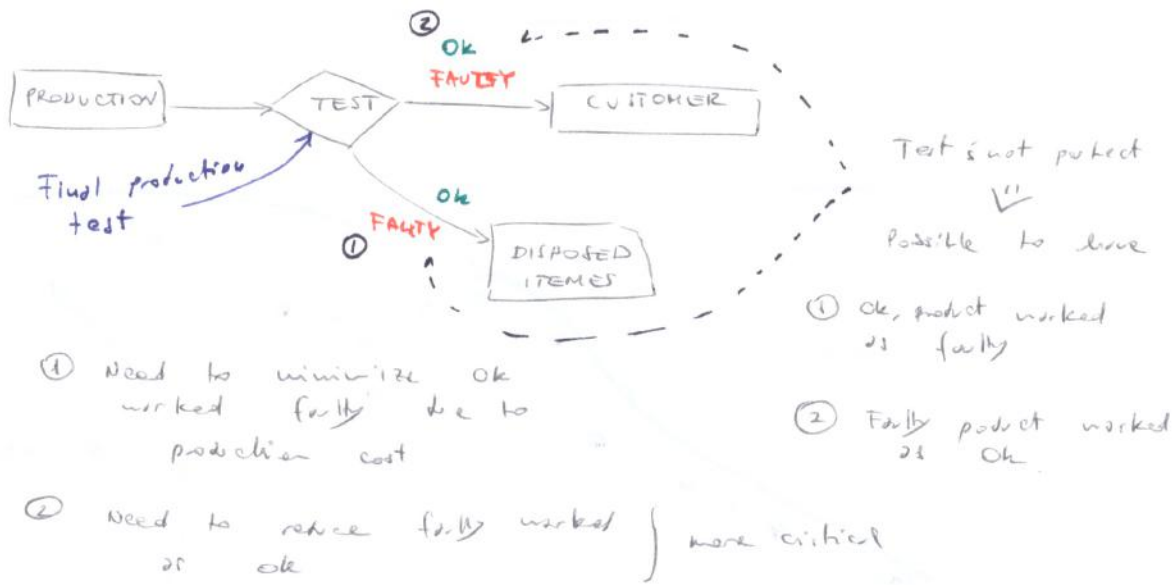
Accepted by Automatic Test Equipment

(ATE)

↳ costly instruments
↓
precise

DEFECT LEVEL = % of faulty devices that pass the test.

- ↳ measured in ppm
- ↳ adaptive to product dependability
- EX.
 - Product for Aerospace \Rightarrow low DF
 - " consumer electronics \Rightarrow decent DF is acceptable



Computation methods

Analytic \Rightarrow Estimation

Experimental

$$\frac{\text{Faulty products}}{\text{Total products}}$$

takes long time
return for the field after enough long time

$$DL = 1 - Y^{1-T} = \text{faulty products pass the test}$$

Y = manufacturing yield
= % of good product

T = Fault Coverage
= how strict the test is
= % of faults detected over the total faults

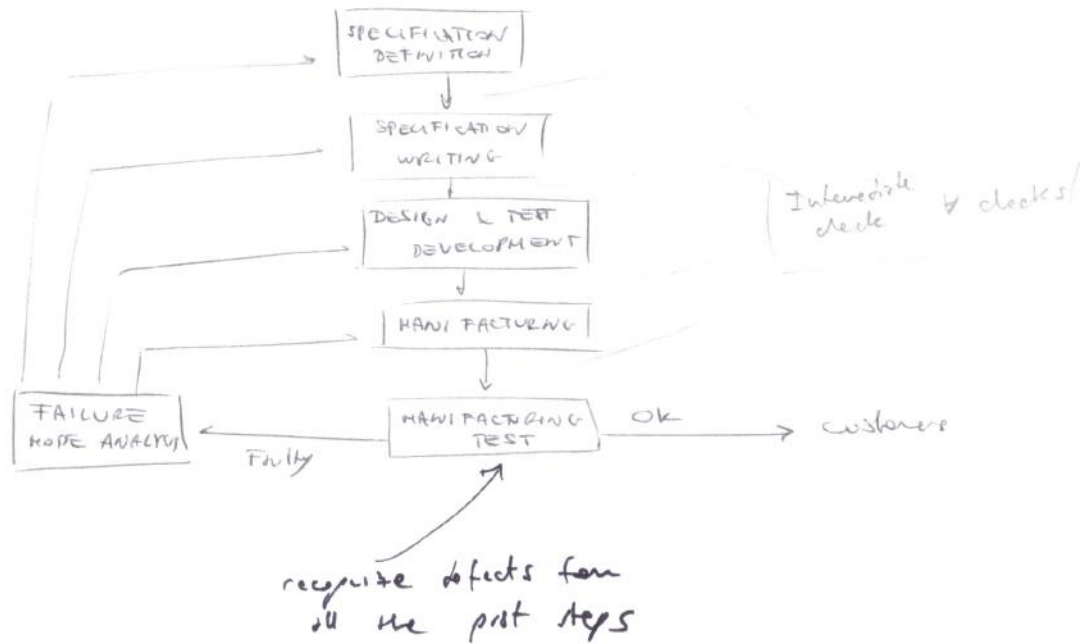
\rightarrow depends on fault-model

After all the production
 N_s = priori estimation
see the faulty product distribution

Computation of DL depends by company and models used.

TESTING IN DESIGN AND PRODUCTION

Faults happen for many reasons \Rightarrow Faults due to \rightarrow production line
 \searrow design phase \leftarrow solved before production starts



INCOMING INSPECTION - tests performed by customer to make sure items work before they use it

Customer don't know the design behind the item \Rightarrow Test performed with limited info.

ON-LINE TEST - item tested when it is used in the working product

Electronics usage deteriorates the components \Rightarrow checky behaviour during the working phase

Performed in order to guarantee or check the system reliability

- No tester used
- Device not removed from the environment

EX. Car ECU

Each few ms a test is performed to check the correct behaviour

\Rightarrow Need of design for testability

2 types

- CONCURRENT = system tested without stopping operation
- NON-CONCURRENT = system tested during idle times or stopping operation.

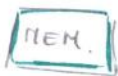
DESIGN FOR TESTABILITY = design unit in order to have easy access to test it.

EX. Memory Test

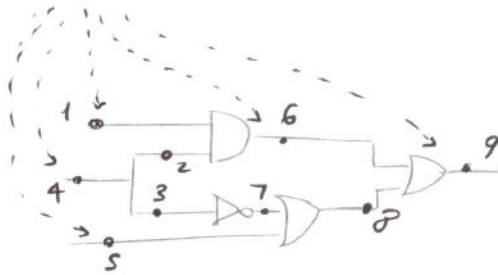
Memory is designed

also a test circuit is designed with memory

Circuit performs a R/W sequence when required and provide a boolean output reporting the test outcome (OK, FAULT)



Stack-at location: point in the circuit where stack-at can occur.

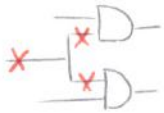


For my stack-at locations we have 2 faulty case $\begin{matrix} s-d-0 \\ s-d-1 \end{matrix}$

We have

$$2M = \# \text{ Faults possible}$$

$$M = \# \text{ checkpoints} = \# \text{ stack-at-locations}$$



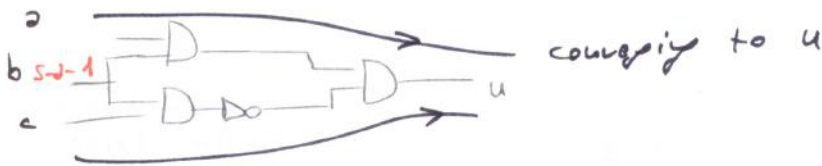
Defect with the same condition but with different observation condition \Rightarrow Different Test vectors

When the faults converge to a single fanout



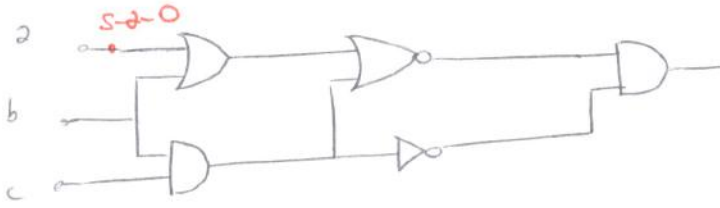
RECONVERGENT FANOUT

EX

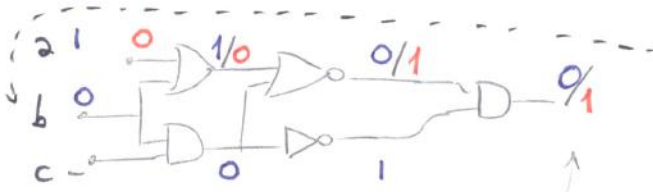


EX 3

$n = 12 \Rightarrow \# \text{ Total Faults} = 24$



$a = s-a=0 \Rightarrow a=1$



$b=0$ in order to make OR gate transparent to the fault

$c=-$ since 0 and 1 are both ok

$0 \neq 1 \Rightarrow \text{Failure}$

$\Rightarrow \{1, 0, -\}$ is a test vector

winning strategy is to make gates transparent to faults



Let's use "transparent rules"

Sites Rules for

For each fault we need to create a failure.

In practice the device is subject to multiple inputs dry times

TEST SET = set of input vectors detecting a fault.

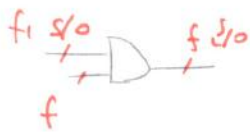
EX.



$$T_f = \begin{Bmatrix} 0 & 0 & 0 \\ 0 & 1 & 0 \\ 1 & 0 & 0 \end{Bmatrix}$$

All these vectors can provoke a failure due to s/1

Sometimes a single vector can detect more than a fault.



$$T_{f1} = \{1, 1\}$$

$$T_{f2} = \{1, 1\}$$

$$T_{f3} = \{1, 1\}$$

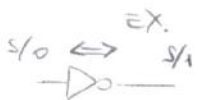
⇒ Same test vectors ⇒ Faults are equivalent

allows to reduce the test list

another way to reduce the test list and make the test easier is via TRANSITIVITY

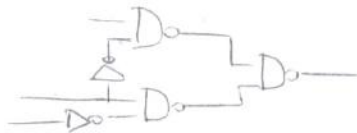
↳ for each gate is possible to reduce 2 faults

based on I/O gate relation.



other gates

EX.

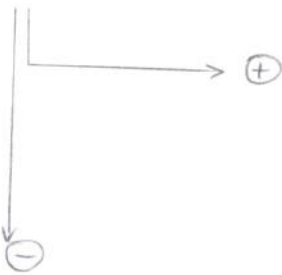


$$n = 10 \Rightarrow \text{Faults} = 20$$

$$\text{gate} = 5 \Rightarrow \text{detectable Faults} = 10$$

$$\text{Fault to Test} = 20 - 10 = 10$$

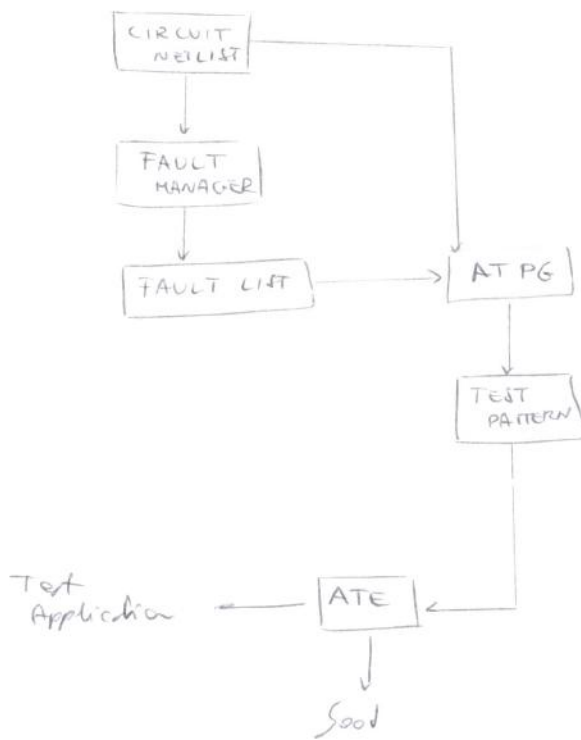
STUCK-AT model is always used in industry



- defects behaves like the model (like 1 way connection to Vcc or GND)
- Supported by CAD tools

- Circuit model open circuits } solved by pattern test.

In general the test procedure is this:



L5 10/20/17

TEST EQUIVALENCE

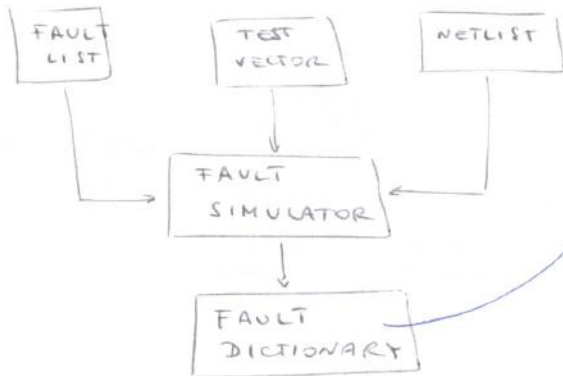
=
two faults have the same test set

FUNCTIONAL EQUIVALENCE

=
two faults have the same functional equation

$$f_{f1} = f_{f2}$$

If Functional equivalence \Rightarrow Test Equivalent
 ~~\Leftarrow~~



Stores faulty circuit behavior given set of TV

n faults \Rightarrow n output sets.

Comparing output from test and scanning the fault dictionary is possible to distinguish the fault.

If

f_{k1}, f_{k2} are functionally equivalent

\Rightarrow $f_{f_{k1}} = f_{f_{k2}}$ = faults modify behavior in the same way

\Downarrow
Hard to distinguish the faults.

If f_{w1}, f_{w2} have some output behavior

\Rightarrow

- f_{w1}, f_{w2} functionally equivalent
- f_{w1}, f_{w2} not distinguishable since \nexists T.V. able to produce different outputs

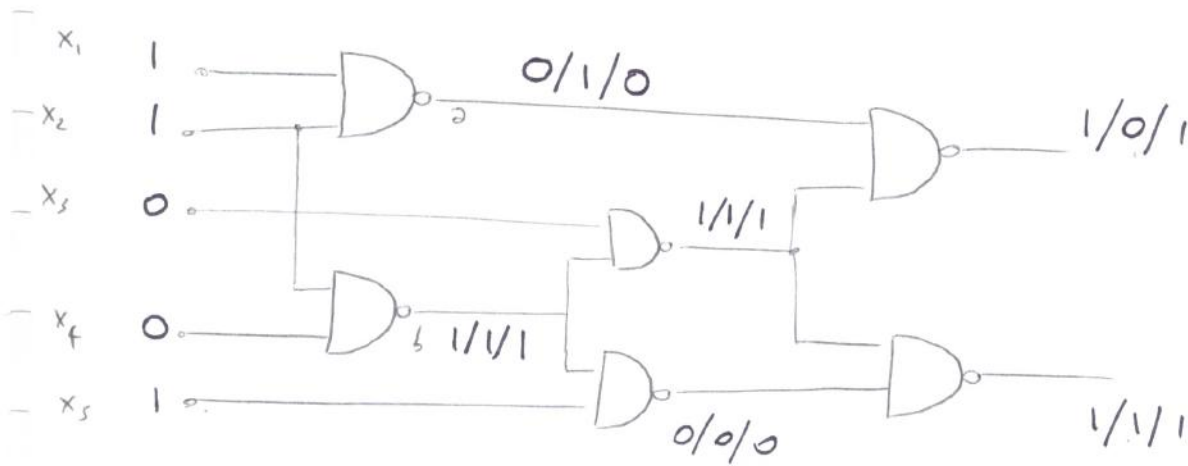
Some time, improving TV is possible to distinguish HW fault if not functionally equivalent

} = Distinguishability

\downarrow
needed for localize faults in a circuit

EX

Identify test vectors to distinguish a/1 and b/1



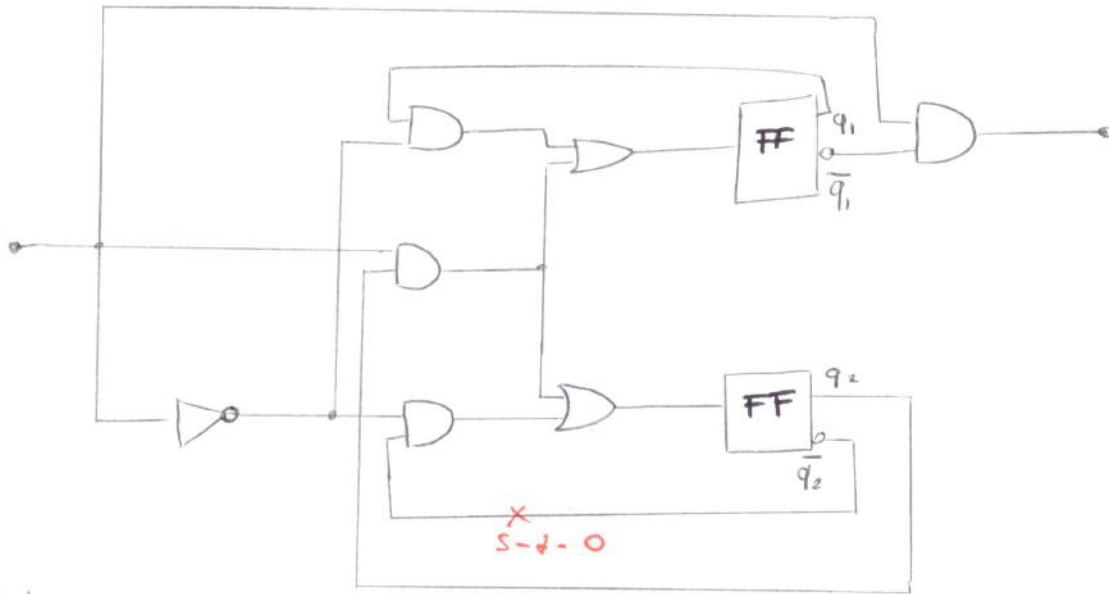
Good c / Circuit with a/1 / Circuit with b/1

If parity $\{1, 1, 0, 0, 1\}$

if $u = \begin{cases} \{0, 1\} \Rightarrow \text{fault responsible is a/1} \\ \{1, 1\} \Rightarrow \text{fault responsible is b/1} \end{cases}$

Some texts provides $TFC = \frac{\# \text{ detectable Faults}}{\# \text{ Tot} - \# \text{ undetectable}}$

EX



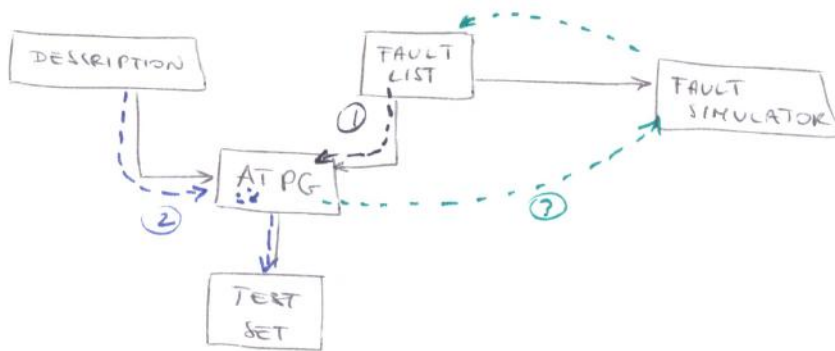
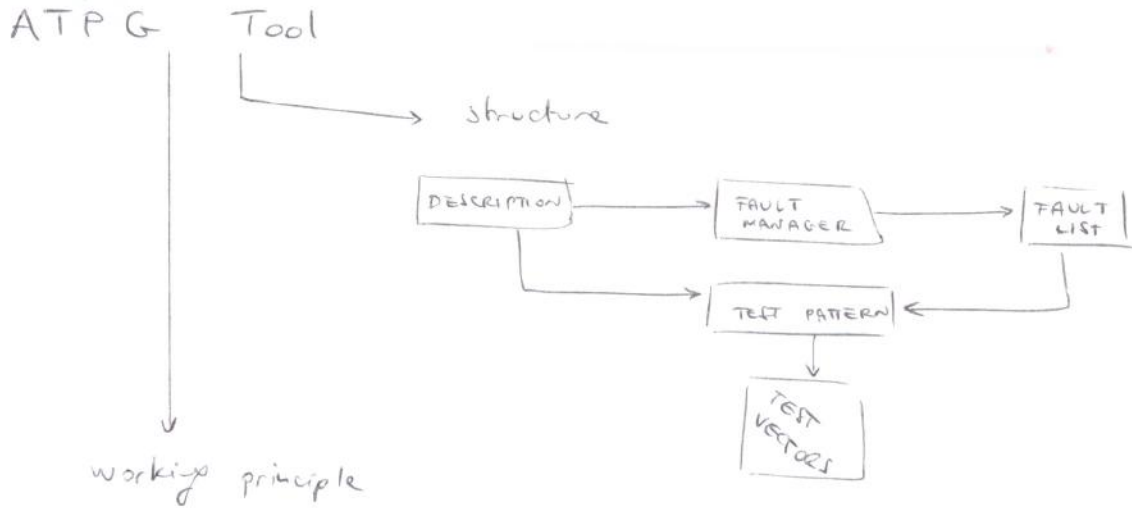
@ start $q_1 = q_2 = 0$

let's assume $S-d-0$

STEP 1: GET $\bar{q}_2 = 1$ TO EXCITING FAULT

$q_2 = 0 \Rightarrow \bar{q}_2 = 1 \Rightarrow$ fault excited *is leads*

STEP 2:



STEP 1: ATPG reads fault from FAULT LIST

STEP 2: ATPG generate a test vector for that fault - using DESCRIPTION

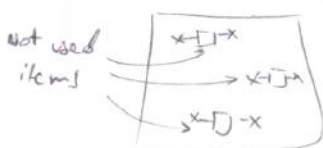
STEP 3: ATPG asks to FAULT SIMULATOR if that test vector simulate the fault, or other faults. FAULT SIM. sets a flag on the simulated fault in the FAULT LIST

helps FAULT DROPPING =

simulation faster
 simulation untested faults only

In order to make testing faster a circuit analysis is performed before start simulation.

Usually a circuit present unused items due to development evolution.



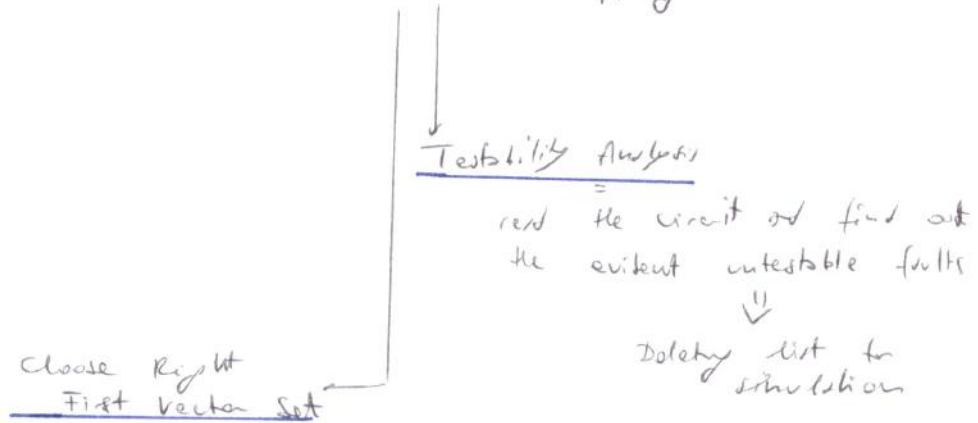
Sales are done and not connected

⇒ Fault there would be untestable

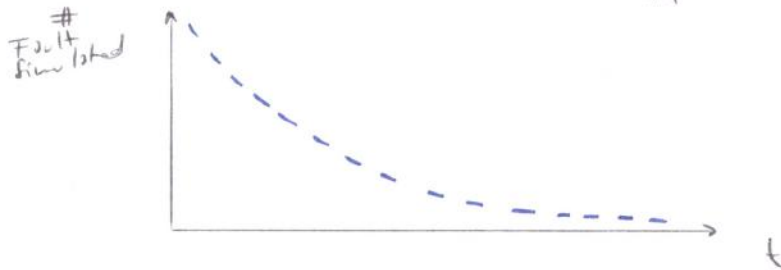
Time Saved.

FAULT MANAGER recognize these faults and do not allow to simulate them

There are some Tricks for Fault Dropping



If there is fault Dropping \Rightarrow t_{sim} reduced



Another good practice is

TEST SET COMPACTION

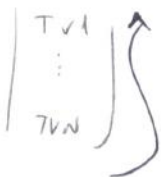
Reverse Order
Fault Simulation

ATPG provides TVc

TV1	f_1	→ detect 4 faults
TV2	f_2	→ detect 3 faults
⋮		
TVN		

we see as we go on less faults would be detected due to Fault Dropping.

Possible to reverse the TVs scanning.



exploiting Don't Care

00_ = 001 and 000

ATPG, however deals with 0,1 only

why we set 00 random?

Random value 0/1 is price @ " - "

NOT TO GOOD

set 0 or 1 based in the most efficient way

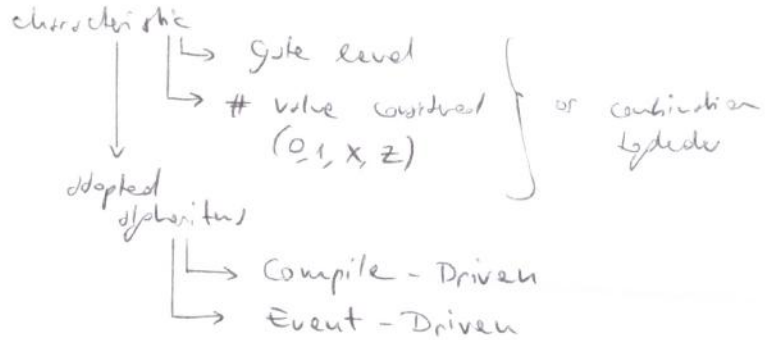
BETTER

If a test vector recognize fault which was already recognized by another TV then it's skipped (no sense simulate then)

LOGIC SIMULATION

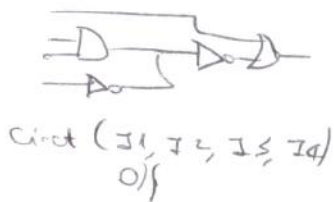
L7 10/30/2017

= sim of fault-free circuit at gate level



• Compile-Driven

= read netlist and write code representing the circuit



- Instruction for each gate
- Variables for I/O and lines

∴ // Instruction

Usually the variable used are char in order to combine with X, Z.

for 0,1 simulation it is possible to exploit the 8-bit char type in order to have multiple test vector applied



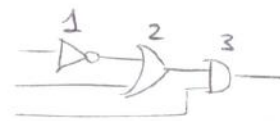
#PIs = 253
 #POs = 372
 #Gates = 123...318 ⇒ 123.318 instructions



PARALLEL GATE SIMULATION

To solve is needed a correct execution order (need gate inputs for computing its output)

Levelization Needed
 = compute low level first to provide the next level the needed inputs



⊕ Very Fast Simulation

⊖ Low probability due to Assembly

- No delay simulation

- For each simulation all gates are re-computed

ATPG

STRATEGY TO SHORT SIMULATION TIME

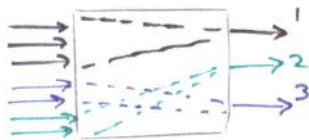
Exhaustive Testing

If PIs < 20 ⇒ All possible combinations are still good for computation

Very Good Test Quality ← All combinations tested

Pseudo Exhaustive

If PIs > 20 ⇒ possible to apply E.T. on some subsets of inputs



1 depends only by black PIs
2 " " " Green PIs
3 " " " Blue PIs

Let's apply E.T. for all the subsets

$$\# \text{ Comb} = \underbrace{2^3}_{\text{by 1}} + \underbrace{2^2}_{\text{by 2}} + \underbrace{2^2}_{\text{by 3}} < 2^7$$

case of ET applied for all the input

Rare cases

Algebraic Methods

Use boolean function of both faulty and faulty-free circuit to get the test set



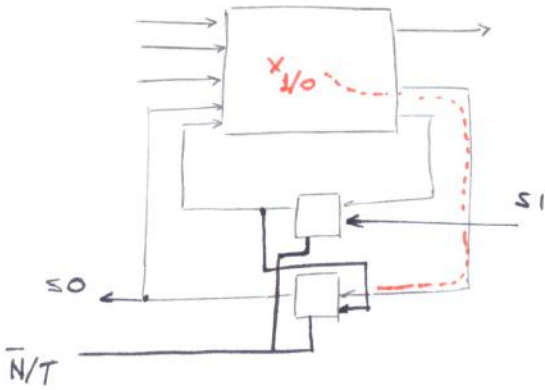
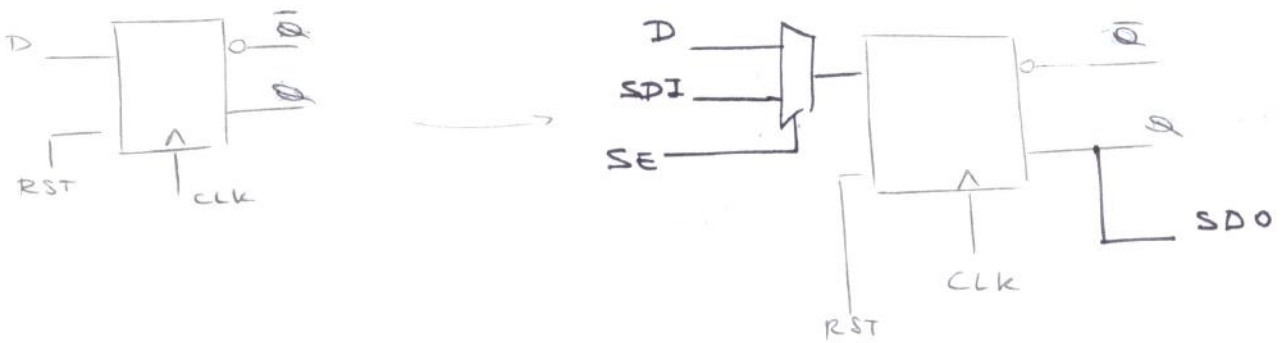
Topological Methods

↳ based on branch-and-bound

Test vector obtained combining fault excitation and observability conditions.

ATPG Good

In order to turn FFs into Shift Register a little HW modification is needed

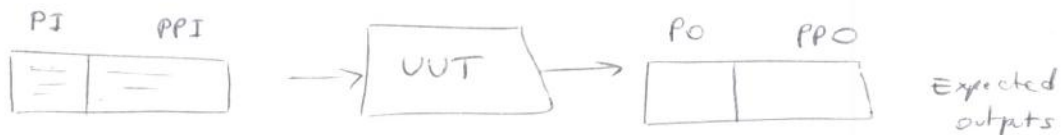


When there is a stuck-at fault, it must be propagated till the FF then insert it in the FF and clock the fault observing SO

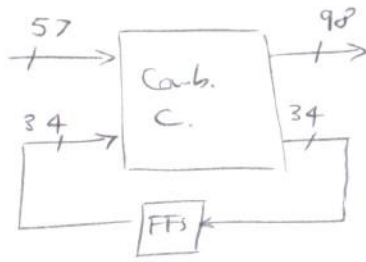
Sequence is:

- Enter Test Mode $\Rightarrow \bar{N}/T = 1$
 - Shift SI
 - Apply Test Vector on PIs
 - Enter Normal Mode $\Rightarrow \bar{N}/T = 0$
 - wait a CLK
 - Read SO
- } test vectors

Test set is generated by ATPG



EX.



TV_s = 315

Test Vector Length = 57 + 34 = 91 bits

Expected Output Vector Length = 98 + 34 = 132 bits

Test Duration for a single TV (CLK) = 34 + 1 + 34 = 69 CLK

↑ Shift IN ↑ Load PI ↑ Shift OUT

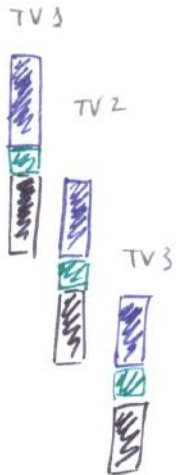
Total Test Duration = 69 CLK · 315 = ... high

Need to make test faster

Costly Test

Let's exploit overlapping between next shift IN and past shift OUT

let's unload the FFs while loading the next scan in



- ⊘ = Scan out
- ↔ = Normal mode
- ⊙ = Scan in

while loading next value the old one are put to scan out ⇒ Total time = (34+1) 315 + 34

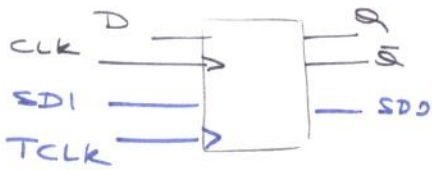
Exploiting overlapping test duration is

Test Duration = M_{TV}(M_{FF} + 1) + M_{FF}

T_{TEST} ≠ T_{CLK} T_{TEST/CLK} ⇐ In test mode the circuit is slower

T_{CLK|TEST} > T_{CLK|OPERATIONAL}

An alternative way to scanning is implementing FFs with dual clock



Operational mode
Testing mode

Basically are two FFs in one

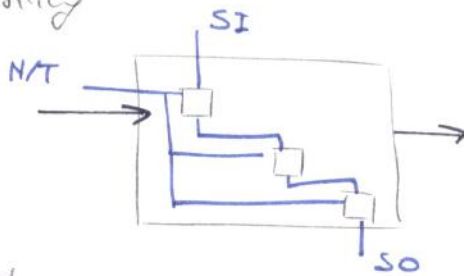
NO T/N bit

2 CLK signal

Not very appreciated by designers

usually not used

Scan testing



Stuck-at can occur also on the scan-chain => before test, test the chain

SHIFT TEST performed

Testception

Steps

contribution to test time:

$$M_{FF} + 4$$

1. Enter Test-Mode
2. Force SI in sequences of 1 and 0.
3. Scan-out and check if SI SO sequences match

Overall time:

$$\text{Shift-Time} = M_{FF} + 4$$

$$\text{ATPG Test} = (M_{FF} + 1)M_T + M_{FF}$$

$$\text{Total Test Time} = (M_{FF} + 1)M_T + M_{FF} + M_{FF} + 4$$

$$= O(M_T M_{FF})$$

$$= \text{Log Time}$$

EX

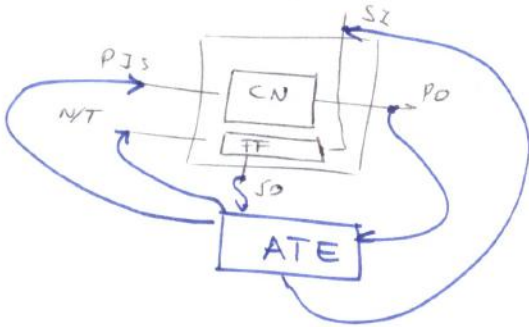
PIS = 107
POS = 212

FF = 2145
TV = 82

Using scan test with only one chain.

1. How is memory size for test?
2. How long does the test take?

1. The situation is:



Automatic Test Equipment has to control the test pins and store the I/O data to check the data.

$\forall TV$ are needed: $107 + 2145 + 212 + 2145 \sim 5000$ bits

\uparrow PIS \uparrow SI \uparrow POS \uparrow SO

$M_{TV} = 82$

$\Rightarrow Mem_{TOTAL} = (107 + 2145 + 212 + 2145) \cdot 82 \sim$
 ~ 500.000 bits

\Downarrow

Memory Needed = 500 kbits

2.

$T_{TEST} \approx M_T \cdot M_{FF} = 82 \cdot 2145 = 175.890 \leftarrow$ Approx

$T_{TEST} = \underbrace{M_T (M_{FF} + 1)}_{ATPG} + M_{FF} + \underbrace{(M_{FF} + 4)}_{Shift-time} = 180266 \leftarrow$ Real Test.

SCAN TEST DERIVATIONS

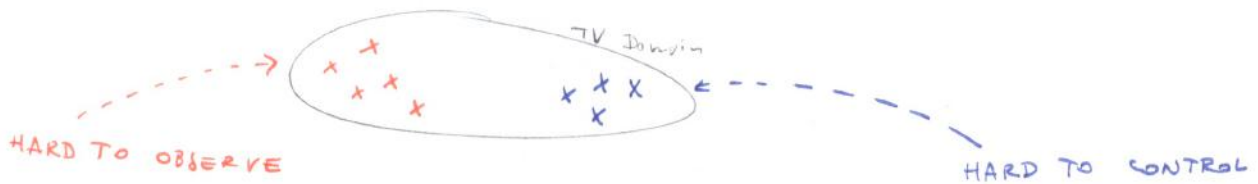
PARTIAL SCAN

= not all FFs are in the scan-chain
 ↓
 No possible to observe those FFs values
 performed because in some FFs the value is
 easy to obtain or possible to reach using
 other ways.
 Not so used, not
 worth it.

TEST POINTS IN DESIGN

If the circuit is large and difficult ⇒ Testing Time is very large
 An aspect of testing is to reduce the testing time.
 ↓
 # TV not be reduced.

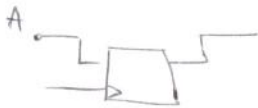
Analyzing the circuit is possible to recognize some test points



A FF is introduced in
 the scan-chain.
 Used only in Test mode
 making the critical fault
 observable

Node is far from PIS
 ↓
 Difficult to obtain
 the wanted result starting
 from PIS

To solve, a FFs internal to
 scan-chain, control the
 hard point in the circuit.



There are additional fault models, not only the stuck-at L9 11/10/17

The main goal of testing is guarantee a given defect level



To have the wanted F.C.
the "endurance" procedure is used

Testing with stuck-at first



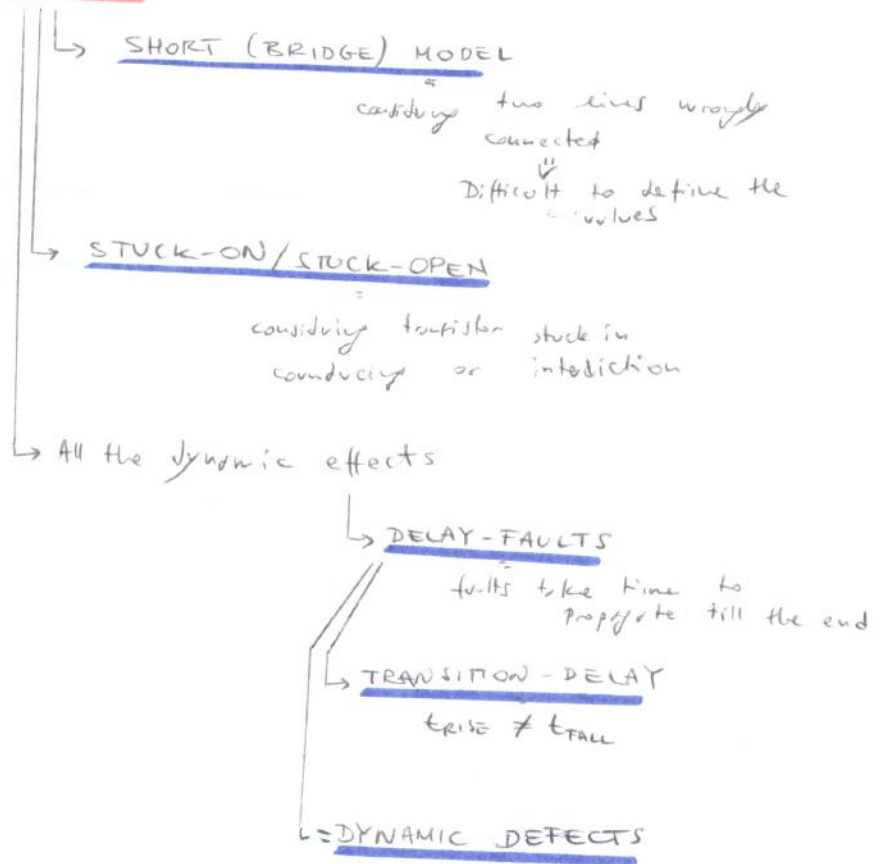
Need to test using other faults models combined with the stuck-at

FC \geq WANTED

Y → Test Done
Stuck-at is sufficient

N →

OTHER FAULT MODELS



• STUCK-ON / STUCK-OPEN = transistors stuck at conductivity or interdiction
↓
looking at gate level

Possible to simulate transistors switching offering that a transistor is stuck in a configuration.

Independently on V_{gs} there are 2 configurations → stuck-on → conductivity
→ stuck-open → interdiction

In a circuit there are million/billion of transistors ⇒ Test them all is never be hard

CELL-AWARE TEST = { usually only a small cell of the circuit is considered for this test

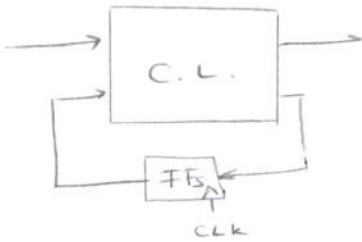
considering only a cell where transistor level is known

Generate T.V. to the cell and check the output.



DYNAMIC DEFECTS

↳ affects the timing required by the circuit to reach steady-state



freq is related to combinational logic delay

Usually $\frac{1}{f} > \Delta$ in order to have the outputs stable.

If there is a delay in the network it could produce a delayed output leading to an error.

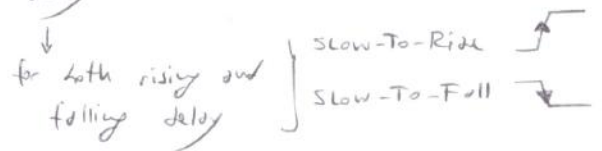
$$\Delta_{\text{DEFECT}} > \frac{1}{f}$$

To test the circuit we need to test it @ $f_{\text{clk max}}$

If test is performed @ $f < f_{\text{max}} \Rightarrow$ possible to not detect any faults

Models

TRANSITION DELAY = model defects as delay

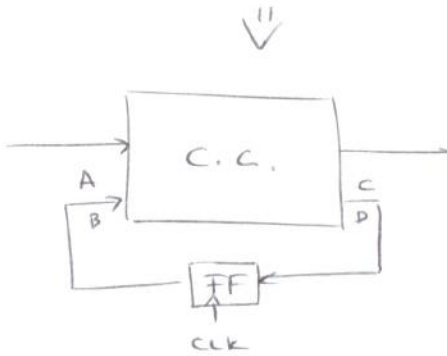


When new input is applied to a gate it takes a bit to have the output result updated

we could have

$\frac{dR}{dF}$ } Provided by library used
 Could change due to fault, but changes are unknown.

Assuming the circuit is a sequential circuit



Assuming that:

$$d = 1 \text{ ns } \forall \text{ gates}$$

$$d_F = d_R = 1 \text{ ns}$$

$$\text{Let's assume 4 poles} \Rightarrow \Delta_{\text{MAX}} = 4 \cdot 1 \text{ ns} = 4 \text{ ns}$$

$$\Delta_{\text{M}} = 4 \text{ ns} \Rightarrow f_{\text{M}} = \frac{1}{\Delta_{\text{M}}} = 250 \text{ MHz}$$

Let's run circuit @ $f_{\text{clk}} = 200 \text{ MHz}$, considering slack

$$t_{\text{slack}} = 0.22 \mu\text{s}$$

$$f = 200 \text{ MHz} \Rightarrow T = 5 \text{ ns} \Rightarrow \text{Outputs C, D sampled @ } 5 \text{ ns}$$

Assuming defect in A causing a 1 ns delayed transition in C.

↓
 very correct sampling would get wrong values and transition won't appear.

To "see" the values FFs are used

TRANSIENT DEFECTS

are difficult to detect, and propagate

If there is a period defect in one and affecting multiple gates

= Distributed Defects → can't be used with transition fault model

requires PATH FAULT MODEL

● PATH FAULT MODEL = considering all possible paths

↓ path all possible transitions must be considered

↓
 check timing of the transitions (both rising and falling)

} in this way all faults are detected

11/13/17

UNTESTABLE DELAY FAULTS

2 types

Structurally untestable

=
No possible to generate couple of vectors just looking the combinational logic

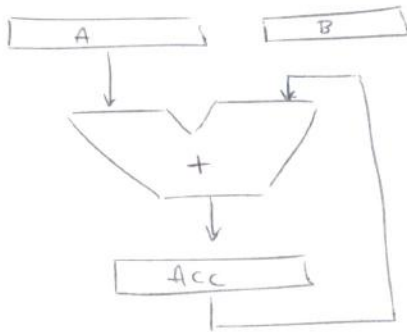
Functionally untestable

=
No access to I/O. Faults can't be tested settings on I/O

EX

Considering multiplication $A \times B$ using only adders

$$A \times B = \underbrace{A + A + \dots}_{B \text{ times}}$$



A, B 8 bits
Acc 16 bits

If we would like to consider a delay fault we need to list all patterns from input until output } looking for critical paths

∇ fault need a pair of T.V. ⇒ Needed V_1, V_2 ⇒ Need values for those Test Vectors

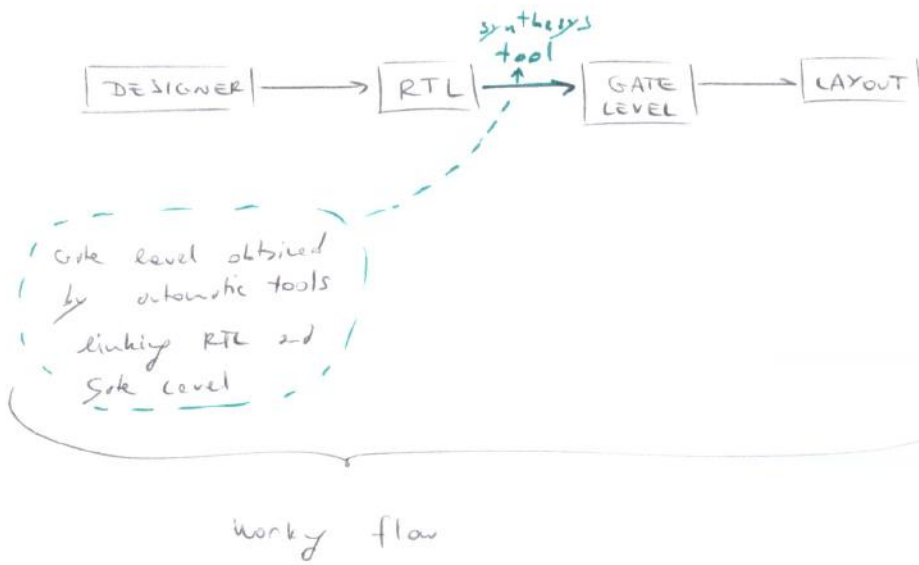
Assume

$$V_1 = \{ \text{-----}, 00000000 \}$$

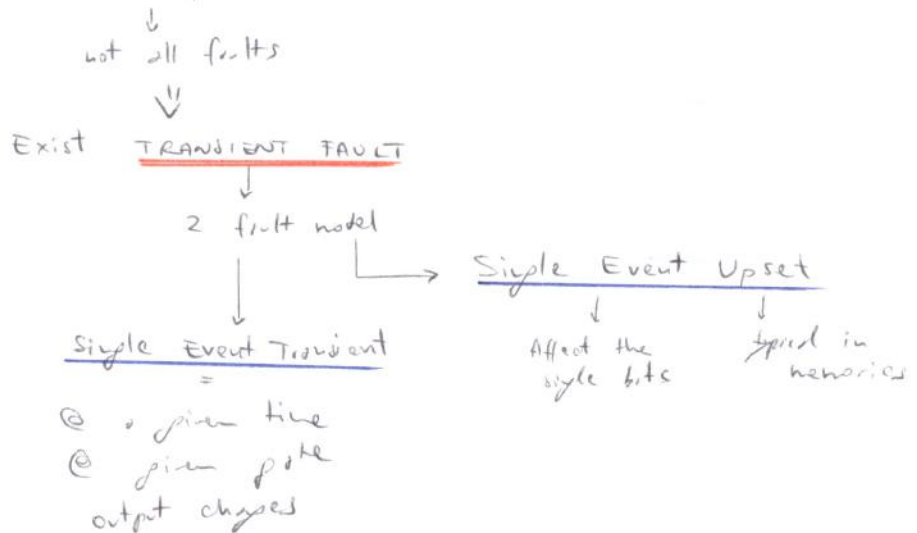
$$V_2 = \{ \text{-----}, 00000001 \}$$

At a given time adder input will pass to 00000000 → 00000001

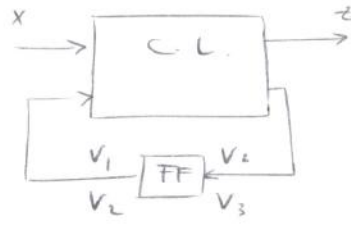
Designer works at the RT level



For now, only permanent faults has been discussed



LAUNCH-ON CAPTURE



Procedure

STEP 1: V_1 scanned in and applied to C.L.
 ↓
 C.L. produces V_2 as output
 ↓
 stored in FFs

STEP 2: V_2 applied to C.L.
 ↓
 C.L. produces V_3 as output
 ↓
 stored in FF

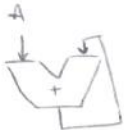
STEP 3: V_3 shifted out

- V_1 freely selected
- V_2 is the response of C.L. to V_1
 ↓
 No possible to apply any vector because V_2 depends on V_1, X .

Risk of overtesting due to V_1 freely chosen but risk is lower.

↳ If sure V_1 is reached in normal behavior \Rightarrow Possible to avoid overtesting

EX



Before shift in a value need it to reach odder inputs

SHIFT-IN $V_1 \Rightarrow$ TEST MODE \rightarrow lower f

CAPTURE $\Rightarrow V_1$ applied to C.L. $\Rightarrow V_2$ produced an output @ NORMAL MODE

CAPTURE II $\Rightarrow V_2$ applied to C.L. $\Rightarrow V_3$ produced an output @ NORMAL MODE

SHIFT-OUT $\Rightarrow V_3$ shifted-out @ TEST MODE

11/17/17

FUNCTIONAL TEST

Testing without design for testability
just apply test stimuli and check the outputs

2 definitions

① Test performed on a product without relying on design for testability

≠

② Test based only on the functions it is expected to provide

Using Functional I/O

Black-Box Model

Depends on

- How to apply the test
- Gray Box Model

Relates to how the test is generated

Used in industries

Roles

IN-FIELD TEST

Test performed periodically when the item is used

Based on Definition ②

EX. Safety Application when faults can downtime.

INCOMING INSPECTION

Making sure that an item, acquired by third parts, is working before integrate it on the design

Buying the item ⇒ No idea about the structure

but using ATE

END-MANUFACTURING

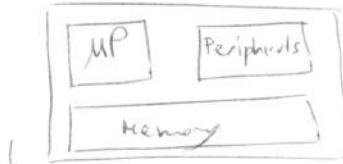
Testing an item when is just made in the factory

Test performed by factory worker and designing the item

Item structure is known

- Assuming a perform functional Test on a SoC
- Functional Test is often used in SoC testing

A SoC



To perform a test MP execute programs involving Peripherals and Memory and observes the results

Basically a μP realize if there is a fault or not.

SoC Testing @ END-MANUFACTURING



Device is on the tester and a certain program is executed

SoC Testing @ IN-FIELD-TEST

In field chip a tester is hard \Rightarrow CPU performs same test program looking for mismatch.

Program is stored in a flash memory

only solution is to run a test program executing the operations producing data stored in memory. Then reading the same memory and look for a mismatch.

If a mismatch is recognized \Rightarrow notification to O.S. asking vendor of faulty circuit.

working principle of an Software-Based Self-Test

- FIFO Testing Steps

- STEP 1: INITIALIZE

initial status unknown \Rightarrow Initialize the FIFO \Rightarrow leads to a known status

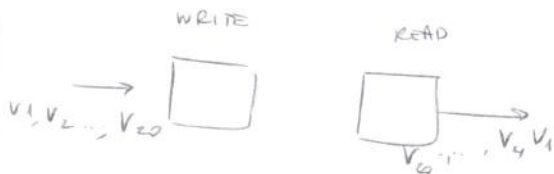
- STEP 2: WRITE

write 20 known values in the buffer or write values until the FULL signal turns high } write different values

- STEP 3: READ

Read 'till EMPTY signal is activated.

- STEP 4: CHECK I/O



Need to line

$$V_{Ij} = V_{Oj}$$

} same output otherwise we have a fault.

- In the functional testing there is no blueprint to perform a test.

- No guarantee to have the entire fault coverage possible since there is a black box.

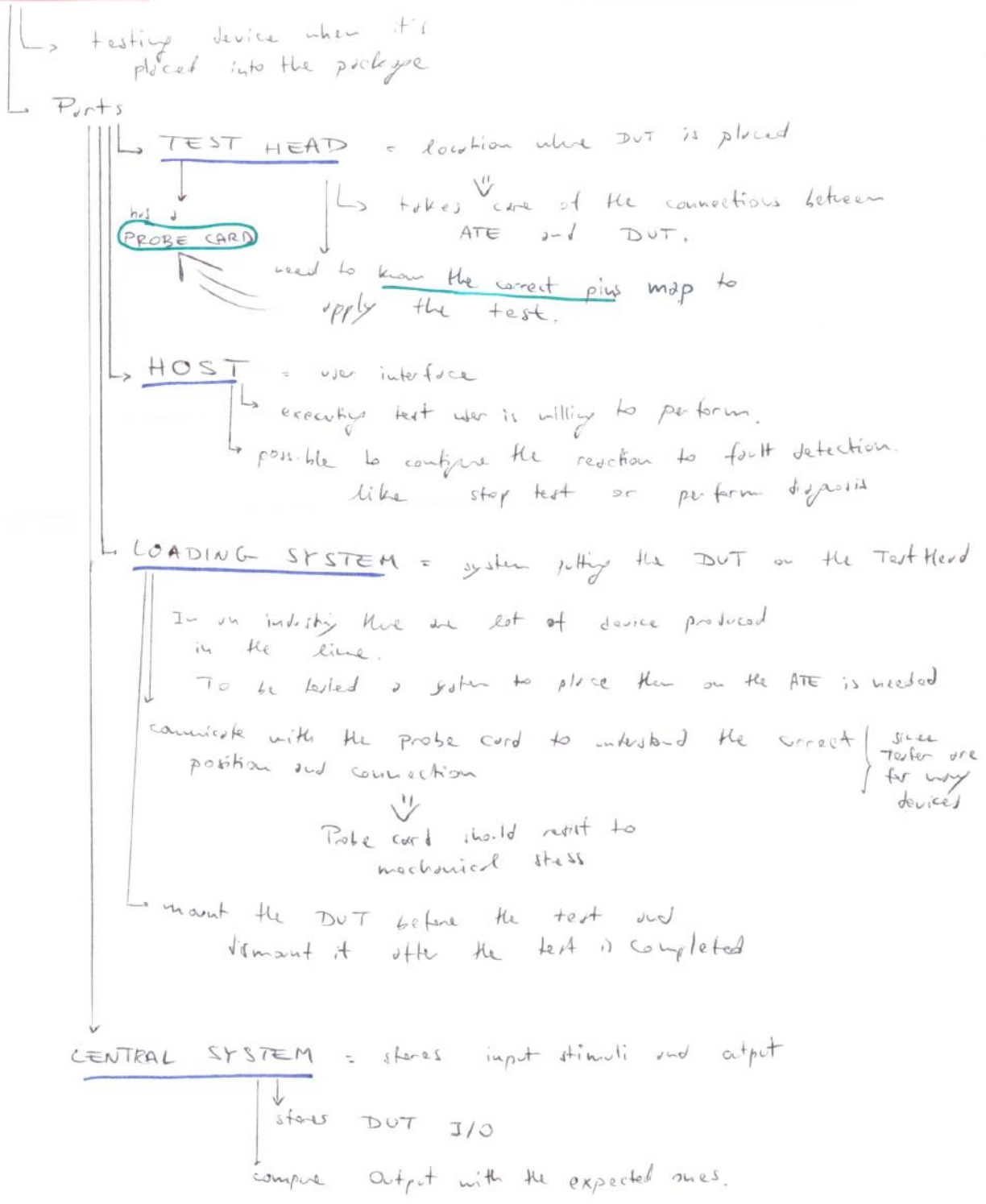


Test vectors usually in layer

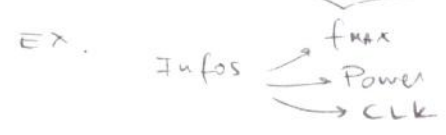


Testing Time layer

ATE for IC Structure



Tester produces set of log files containing test infos and results.
 ↓
 can't contain all the info he to log
 test = log log files.



Let's imagine to test a memory circuit

Memory Test = Perform W/R operations

Memory uses addresses to select where perform the operation

Need a tester storing the memory address } Feature in tester for memories

Before use the tester is better to test it

Again fault/test inception = "what if tester is faulty?"
(yes, like the movie) "How to test a thing designed to test?"

Solved (or partially) using some Test operation Sequences List

Check V, I on pins in order to check the system } = Steady State Pin Parametrics
Making sure all pins are connected

Test correct behavior of the tester before using it } = Test Logic Verification

Apply vectors and combinations of scan Test Functional Test } DC Logic Stack-up

Check if memory elements are able to store informations } DC Logic Retention
How much the memory is able to keep those values

Test Program = programming the tester in order to perform the wanted operation during the testing phase

needs info like

- start/stop Time
- Input values to be applied
- Expected output values to be applied

Written using specific languages compatible with CAD tools.

EX.

STIL = language used to describe vector

STDF = language describing test program.

Pin Timing = synchronize operations according to CLK

↳ specified for Pin by test program

In theory CLK is unique and single one

In practice ≠ CLK enters test unit providing others and different clock signal

• sometimes Tester required the DUT fclk.

Test Plan = how test is going to evolve

Test complex => Better understand the test phases order deciding the steps to use

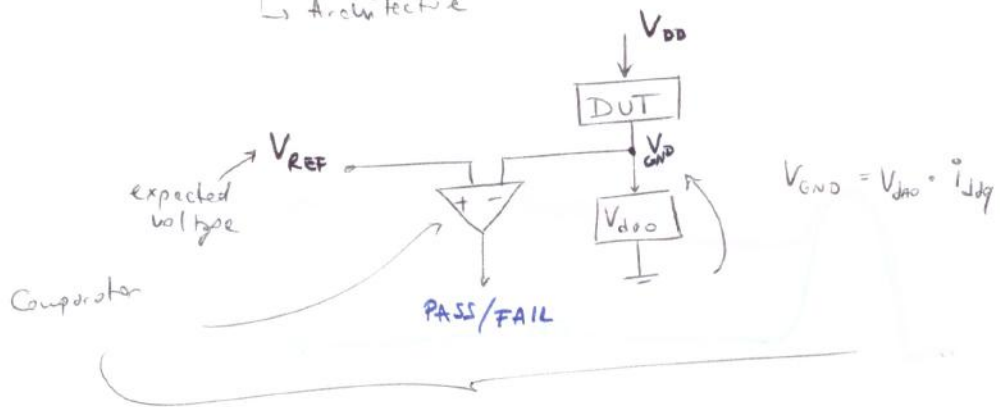
Parameters tuning

- ↳ Threshold Current = value selected in interval $1\mu A < I_{dpp} < 20\mu A$
 Depending on experience
- ↳ Observation Time

To measure current in Test Phase a good Tester is needed

↳ = Bit-In Current Sensor

↳ Architecture



looking at voltage \Rightarrow simpler kind of design for testability

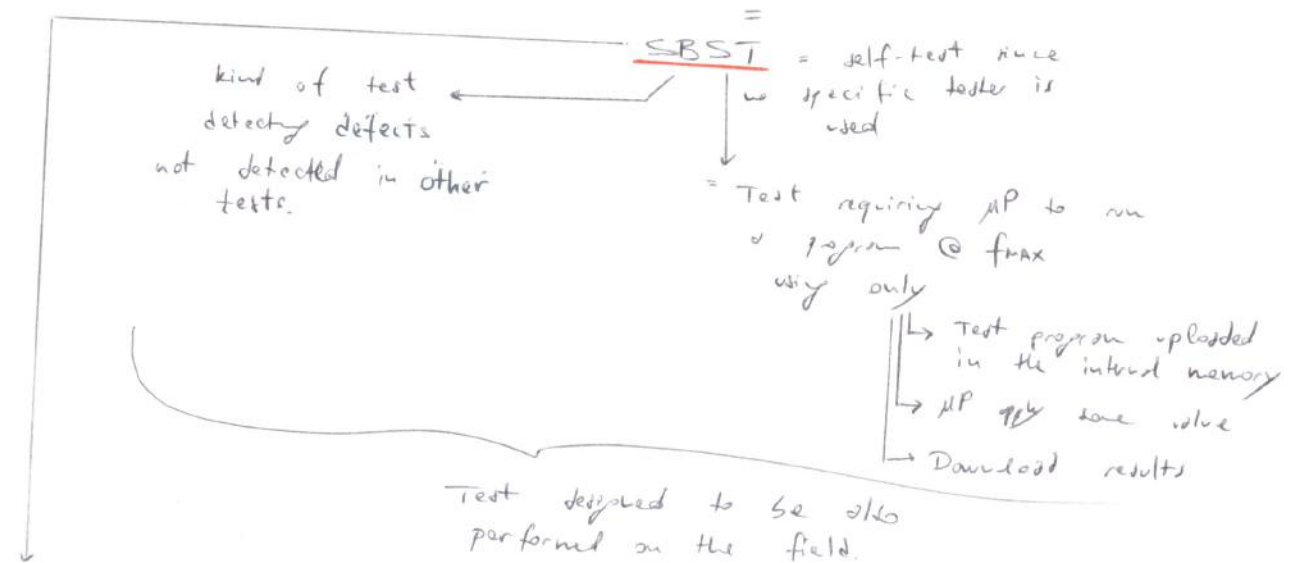
Experimentally

HP performs 3 testing type

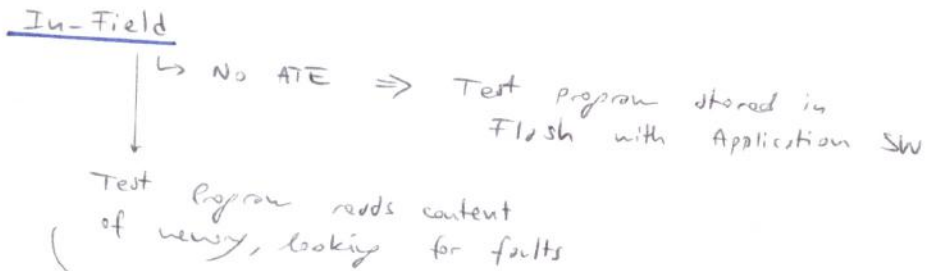
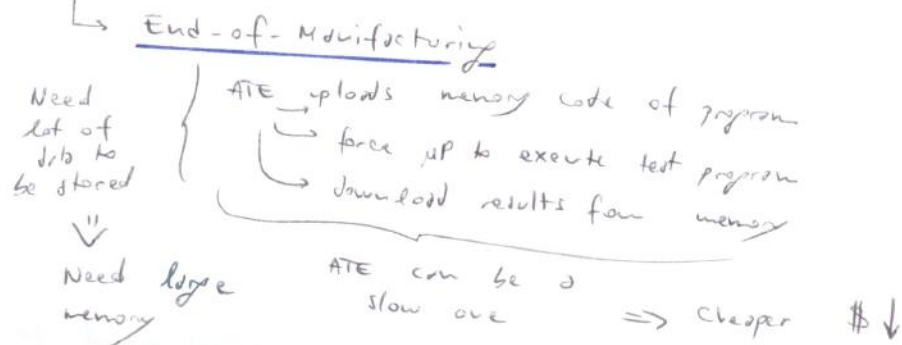
- ↳ Full Scan
- ↳ I_{dpp} Test
- ↳ Functional Vectors

11/20/17

Test μP , SoC using Functional test \Rightarrow Use the CPU to execute a test program and check if results are ok or not



used in 2 scenarios



Test Program is completely autonomous.

```

initialize (&signature)
for (i=0; i < 256; i++){
    for (j=0; j < 256; j++){
        signature = compact (z=i+j);
    }
}
if (signature != exp_signature){
    error();
}
    
```

Apply all the possible values for i, j and perform addition.

Save result in z

store values and compare with the expected one takes TOO MUCH space

Better compute

SIGNATURE

ALU returns a value signature tells if there are faults.

Just need to check the final signature

Read whole memory for checking values

way to compute

ASSEMBLY

EXOR

just perform z EXOR SIGNATURE

```

int opd1 [N], opd2 [N], res [N];
int adder_test (void) {
    int i, x;
    for (i=0; i < N; i++){
        x = opd1 [i] + opd2 [i];
        if (x != res [i]) {
            ERROR()
        }
    }
}
    
```

opt1, opt2 two vectors when values to be applied are stored

- Reading values from operand and store results in the memory
- Scan vectors to detect values

If ALU structure is known

⇒

Isolate ALU and run

⇒

Test vector to be applied need to be stored in opt1, opt2

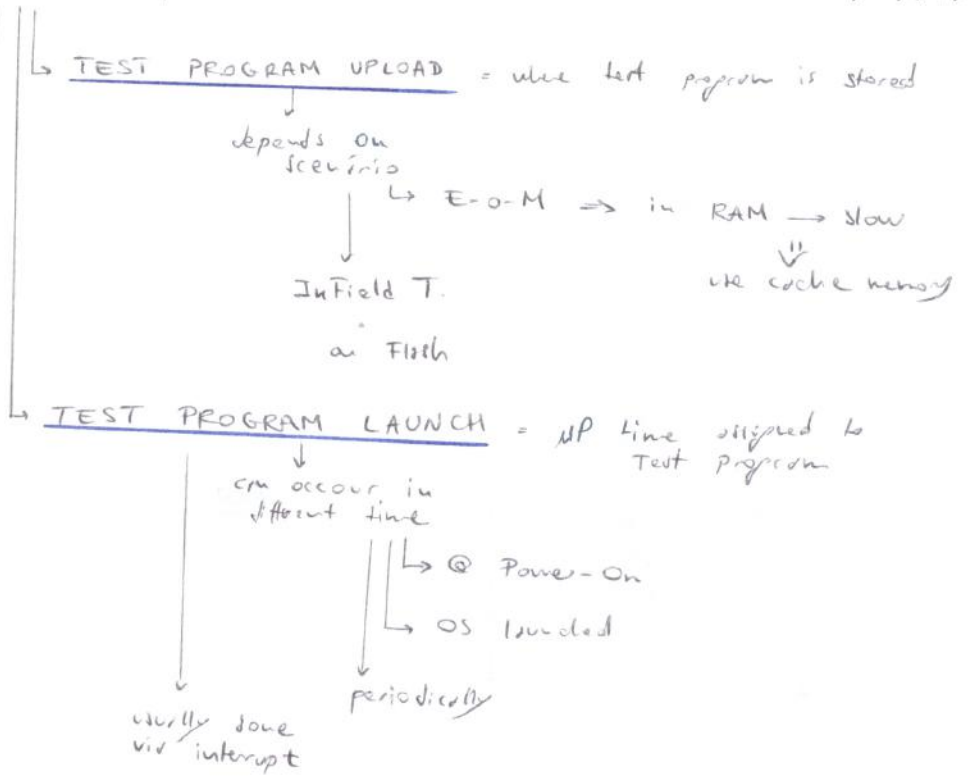
8 instructions has to be executed

⇒

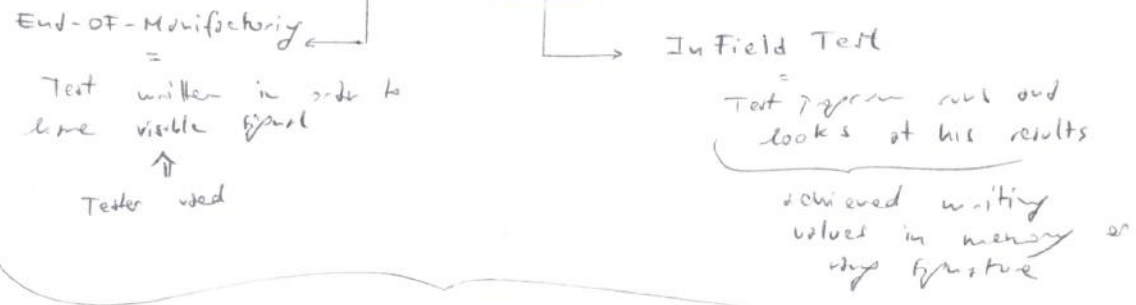
TEST DURATION = 8 · M_{VECTOR}

SBST has 3 critical point

11/24/17

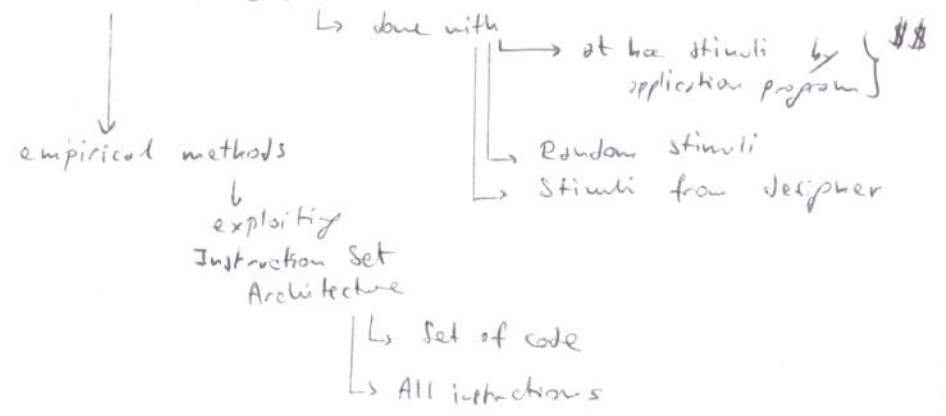


TEST EXECUTION AND RESULT COLLECTION = how to observe results



All these issues must be solved during test application

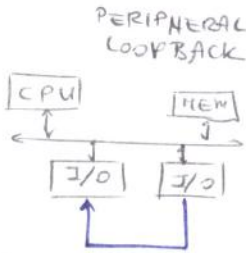
Major problem = GENERATING TEST PROGRAM



PERIPHERAL

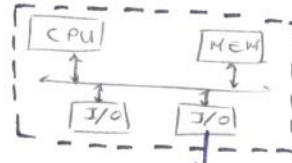
↳ tested using functional test ⇒ need to execute/observe peripheral for outside.

2 ways
 ↳ PERIPHERAL LOOPBACK
 ↳ ATE



Test with at a tester one I/O generates outputs while other looks if match with the connected one

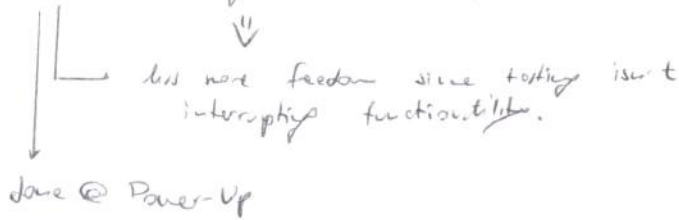
- \$\$\$↓
- Some stimuli can't be detected



ATE force peripheral to send/receive data

- \$\$\$↑
- Flexible

TEST @ START = testing before the system starts its routine operations



however test should be short in time.

CRITICAL UNITS = are critical in In-Field-Test

list
 ↳ Address Calculation Unit

memory access if wrong address is faulty the access to memory will be wrong.

possible to check with/ready
 & position of memory not reserved
 ↳ 0.5

11/27/17

BIST Built-In Self Test

=
Embed into the system to test itself without anything from the outside

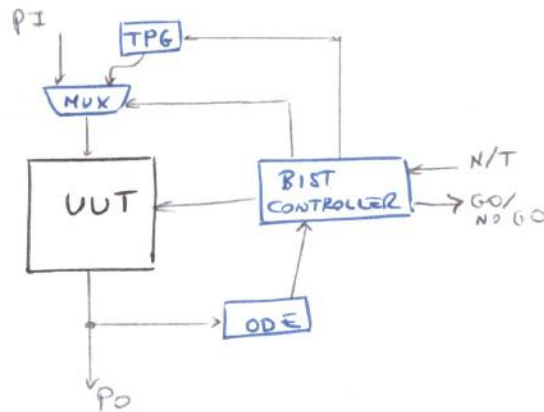
⇓
No need for Testers

type of design for testability



Special Circuits setting the whole circuit in "Test-Myself" mode.

→ System Architecture



TPG = Test Pattern Generation
↳ generate values to perform the test

MUX
↳ select PIs in Normal Mode or T.V. in Test Mode

BIST CONTROLLER
↳ manage different module in both test and normal modes

ODE = Output Data Evaluation

↳ compare the output with the expected values and notify the comparison outcome to BIST CONTROLLER

⇓
Outside testers not needed but just activate test mode

Assuming UUT is Combinational circuit

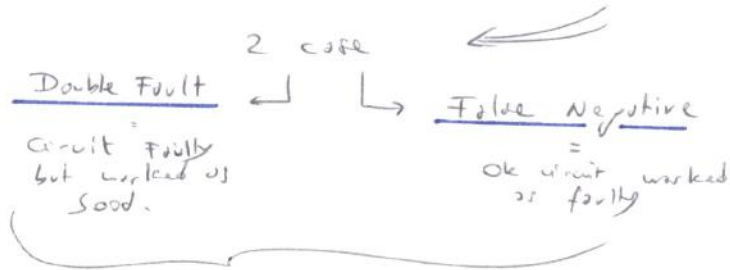
- ⇒ • # Input not large ⇒ possible to execute exhaustive test
- Test Pattern Generation is counter
- ODE computes signature of the output with the expected ones.

→ Implementation

- ↳ Combinational Circuits
- ↳ Sequential Circuits
- ↳ Memories

BIST is based on circuit

⇓
possible faults on it. ⇒ BIST circuit would provide a wrong outcome.



both no good

⇓
Test BIST

↓
strategies

↳ Duplicate NIT (no/yes) pins with complementary values.

BIST's Goals

- ↳ Test itself ⇒ Avoid to perform wrong test due to faulty test circuit
 - ↳ Minimize
 - ↳ 2/0
 - ↳ Test Time
 - ↳ HW.
- used in InField-Test

Better Describe the behavior using polynomial algebra

Given an $(m+1)$ bit vector $R = [a_m a_{m-1} \dots a_2 a_1 a_0]$

possible to write it into a binary polynomial

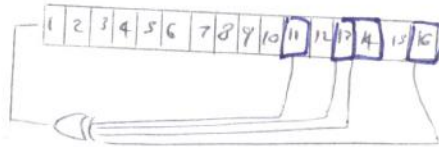
$$P(x) = a_m x^m + a_{m-1} x^{m-1} + \dots + a_1 x + a_0$$

$$a_i = \begin{cases} 0 & \Rightarrow \text{Open Circuit} \\ 1 & \Rightarrow \text{Closed Circuit} \end{cases}$$

possible to create vector depending on where when feedback line exists.

EX

Selecting only $a_{11}, a_{13}, a_{14}, a_{16}$



⇓

$$P(x) = x^{16} + x^{14} + x^{13} + x^{11} + 1$$

TH.

If characteristic polynomial is a primitive polynomial
 ↓
 can't be divided in other polynomials

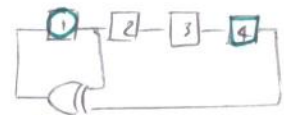
⇒

Possible to generate a LFSR that will evolve through all the states before repeating the sequence

EX

Consider the polynomial of degree 4 $P(x)$

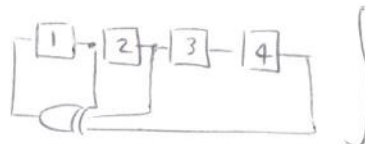
$$P(x) = x^4 + x^1 + 1$$



there are many primitives for degree 4

for example

$$x^4 + x^2 + x + 1$$

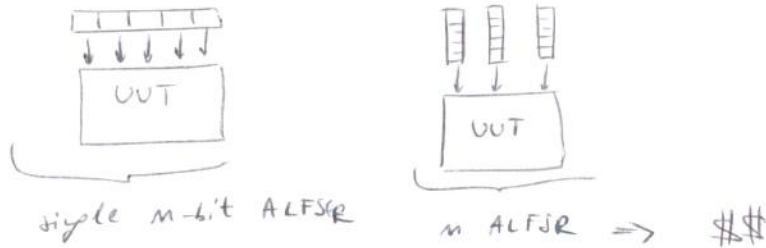


New connection required = \$\$\$

POSSIBLE FOR DEGREE < 20

So it is to find high degree requiring few...

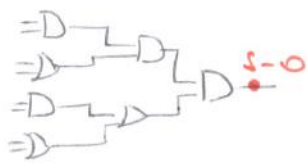
ALFSRs used in practice:



In some cases

Bias the input values ⇒ Speed up F.C.

Assuming UUT = Tree Gates



we got a stuck-at-0 I need 1 in all inputs

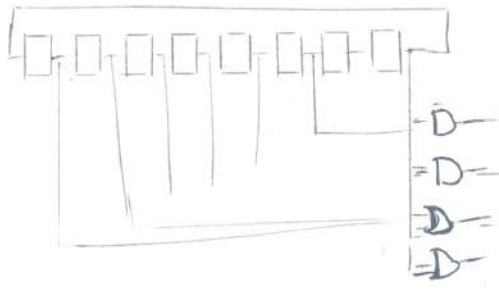
if using a LFSR need to wait till period 11...11..

Better to BIAS the input
 ↳ loop time wasted

Need a WEIGHTED (BIASED) RANDOM GENERATOR

↓
 faster convergence to $\approx 100\%$
 ↳ Biasing probability

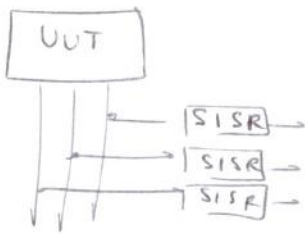
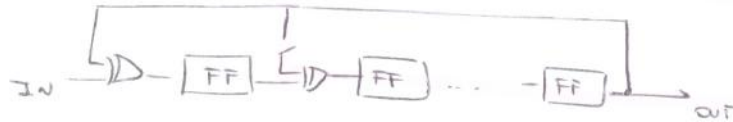
Architectures



output would be random anyway

ODE implemented using Single Input Shift Register

Always to put bit into the circuit \leftarrow LFSR which is similar to cellular architecture but EXOR is an input



\forall SISR signature is computed

When testing a board \Rightarrow apply input stimulus and observe the outputs

Several a faulty free board is tested and signature is computed.
 \downarrow
 used for references.

Low aliasing probability before test a board

Given 2 Input sequences \Rightarrow ALIASING = P("2 signature are the same")

SISR can be represented using polynomials

Given

$$\frac{G(x)}{P(x)} = Q(x) + \frac{R(x)}{P(x)}$$

$\Rightarrow R(x) = \text{Reminder}$
 = Bits in FFs at the end of the experiment.

$G(x) = \text{Input sequence}$
 $Q(x) = \text{Output sequence}$
 $P(x) = \text{LFSR polynomial}$

Goal = find a characteristic polynomial such that remainder of the division is different from the others as much as possible

Better define Polynomial Error $E(x)$
 $E(x) = G'(x) - G(x)$

$$E(x) = G'(x) - G(x) \Rightarrow R(x) = R'(x) \Leftrightarrow E(x) = mP(x)$$

If $P(x)$ is correctly selected \Rightarrow possible to maximize probability of different signature

HASHING SIGNATURE $P_M = \frac{2^{m-n} - 1}{2^m - 1}$